ASOCIATION CONNECTING ELECTRANCE INDUSTRIES INTERNAL Material Composition I © Copyright 2005. IPC, Banno international and Pan-American	ekburn, Illinois, A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	tion of the s encompasse	ubstances es all lowe	within the mar er level materia	nufacturer li ls for which	isted item. Note that the manufacture of the manufa	ote: if the cturer has	e item is an ass s engineering re	embly with lower sponsibility.
2-21.1 IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distributed				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplier Information													
Company name* Company unique ID				Unique ID Authority					Re	Response Date*			
isemi										2025-06-04			
Contact Name	Title - Contact			1	Phone - Contact*				Er	Email - Contact*			
Product-Env-Stewards	-Env-Stewards Product Enviro Compliance			NA				P	Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative				Phone - Representative*				Er	Email - Representative*				
Product-Env-Stewards Product Enviro Compliance					NA				P	Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr I	em Number	Mfr Item Name			Effective Dat	e Version		Manufacturing Site		Weight	t*	UOM	Unit Type
TS39	DR2G Micropower Dual CMOS Comparator		l CMOS Voltage	;	2025-06-04					72.0		mg	Each
Manufacturing Proccess Information													
Terminal Plating / Grid Array Material	Terminal Base Alloy J-STD-020 I			Rating	Peak Process Body Temperature Max Time at Pea			at Peak Ten	Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Alloy 1		1		260		С	30		seconds 3	3			
Comments													
level 1 - maximum time at peak temperature during	soldering is 10-3	0 seconds											
For more information regarding material compositi	on please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

				ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
sigma range of distribution unless	s otherwise noted).	it of the substance of the f		[1] Optionally enter the positive (1) and h	egative () toterance in per	cent (110te: percer	n tolerance varues are	
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg	Supplier	Silver (Ag)	7440-22-4		1.8	mg
			Supplier	Epoxy resins	129915-35-1		0.6	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.7898	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0752	mg
			Supplier	Iron (Fe)	7439-89-6		0.9403	mg
			Supplier	Copper (Cu)	7440-50-8		35.8047	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		1.429	mg
			Supplier	Phenolic Resin	Proprietary Data		1.429	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.0075	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Au	0.19	mg	Supplier	Gold (Au)	7440-57-5		0.19	mg